

Title (en)
SEMIFINISHED PRODUCT FOR POPULATING WITH COMPONENTS, METHOD FOR POPULATING SAME WITH COMPONENTS, AND USE OF THE SEMIFINISHED PRODUCT

Title (de)
HALBZEUG ZUR BAUTEILBESTÜCKUNG, VERFAHREN ZUR BAUTEILBESTÜCKUNG UND VERWENDUNG DES HALBZEUGS

Title (fr)
PRODUIT SEMI-FINI DESTINÉ À ÊTRE REMPLI AVEC DES COMPOSANTS, SON PROCÉDÉ DE REMPLISSAGE AVEC DES COMPOSANTS ET UTILISATION DU PRODUIT SEMI-FINI

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Abstract (en)
[origin: WO2021043855A1] The invention relates to a semifinished product (6) for populating with components, or on which components are encapsulated, more particularly for populating a power electronics component that can be produced by a jointing technique such as pressure sintering, and to the use of the semifinished product (6) in a jointing method for the assembly of semiconductor components. As a result of the invention it is possible, for the first time, to produce a fully sealed, insulating encapsulation in a single process step, by pressure sintering for example. To this end a semifinished product (6) in the B-stage is applied around the sintering material (3) prior to pressure sintering. The invention is characterized above all by the capability to electrically connect and electrically isolate simultaneously in a single operation, preferably by pressure sintering, when assembling semiconducting components (7).

IPC 8 full level
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